

MAP2009 Program Overview

Wednesday 11 th November, 2009		
Time	Presentation @Argos B	Poster Exhibition @Argos A
13:00 ~ 13:05	Opening Remark	Poster & Exhibition
13:05 ~ 15:00	Session 1*: Invited Talks	
15:00 ~ 15:30	Coffee Break	
15:30 ~ 15:50	Signing Ceremony of Memorandum of Understanding between ASTSA & MEPTEC	
15:50 ~ 16:00	Coffee Break	
16:00 ~ 17:40	Session 2: Green Device	
17:15 ~ 17:40	Coffee Break	
17:40 ~ 18:20	Session 3:3D Integration -Part 1- (Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)	
18:30 ~ 20:00	Reception Party @Tinga Tinga	
Thursday 12 th November, 2008		
09:00 ~ 09:55	Session 4*: Power Electronics	Poster & Exhibition
09:55 ~ 10:20	Coffee Break	
10:20 ~ 12:30	Session 5: 3D Integration -Part2- (Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)	
12:30 ~ 13:30	Lunch Break	
13:30 ~ 15:00	Session 6: Taiwan Session (Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)	
15:00 ~ 15:30	Coffee Break	
15:30 ~ 17:10	Session 7*:India Session	
17:30 ~ 19:00	Session 8 : Poster Session with Wines @Argos A	
Friday 13 th November, 2009: Excursion in KUMAMOTO		
10:00 ~ 12:00	Tokyo Electron Kyushu Limited, Head Office, Goshi Plant	
13:30 ~ 15:30	Mitsubishi Electric Corporation, Power Device Works, Kumamoto Plant	

*Supported by JETRO Regional Industry Tie-up (RIT) program.

MAP2009 Program

Wednesday 11th, November

13:00 ~ 13:05 Opening Remark

Hajime Tomokage

Fukuoka University (JAPAN)

13:05 ~ 15:00 Session 1*: Invited Talks

Chair: Todd Takaki

Inoueki., Ltd. (SINGAPORE)

13:05 ~ 13:45 1-1 Present and Future of Digital Technology

Junshi Yamaguchi

NEC Electronics Corporation (JAPAN)

13:45 ~ 14:00 1-2 Electronics Industry in India-an Overview

N Krishnan

Software Technology Parks of India (INDIA)

14:00 ~ 14:30 1-3 Overview of the Indian Automotive Industry: The growth of Mahindra Group

Vishal Pawar

Mahindra Engineering Services Ltd. (INDIA)

14:30 ~ 15:00 1-4 Current and Future Strategy of Semiconductor Industry in the U.S.A.

Joseph Fjelstad

Verdant Electronics and Silicon Pipe (U.S.A.)

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15:00 ~ 15:30 Coffee Break

15:30 ~ 15:50 Signing Ceremony of Memorandum of Understanding between ASTSA & MEPTEC

15:50 ~ 16:00 Coffee Break

16:00 ~ 17:40 Session 2: Green Device

Chair: Masahiro Kashiwagi

Kumamoto Industrial Research Institute (JAPAN)

16:00 ~ 16:15 2-1 Recent Technology of Organic Electro-Luminescence(OEL)

Kiyoshi Yoneda

- FPD Technology Consultant (JAPAN)*
- 16:15 ~ 16:30 2-2 CMOS Camera Module Technology Trend for Mobile Application
Tomoaki Iizuka
Toshiba Corporation, Semiconductor Company (JAPAN)
- 16:30 ~ 16:45 2-3 Colorful and Plastic Solar Cells for Ubiquitous Power Generation
Tsukasa Yoshida
Gifu University (JAPAN)
- 16:45 ~ 17:00 2-4 Our Latest Model FS3500N – Short Cycle Time of 1.7 sec/chip is Attainable in Combination with High Alignment Accuracy of $\pm 2\mu\text{m}$, by Our Original Function and Highly Stiff frame Structure.
Fuhito Shinji
Toray Engineering Co.,Ltd. (JAPAN)
- 17:00 ~ 17:15 2-5 Laser Scribing of Hard and Brittle Materials (Sapphire, GaN, SiC)
Shohei Nagatomo
Laser Solutions Co., Ltd. (JAPAN)

17:15 ~ 17:40 Coffee Break

17:40 ~ 18:20 Session 3: 3D Integration -Part 1-

(Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)

Chair: Yoshio Nogami

Toray Engineering Co., Ltd. (JAPAN)

- 17:40 ~ 18:00 3-1 Standardization of Device Embedded (Both Active and Passive) Electronic Circuit Board Technology
Akikazu Shibata
Japan Electronics Packaging and Circuits Association (JPCA) (JAPAN)
- 18:00 ~ 18:20 3-2 Application and production scenario of TSV-3D Technology
Hirohisa Matsuki
Fujitsu Microelectronics Limited (JAPAN)
Japan Electronics and Information Technology Industries Association (JEITA) (JAPAN)

18:30 ~ 20:00 Reception Party @TINGA TINGA

Thursday 12th, November

09:00 ~ 09:55 Session 4*: Power Electronics

Chair: Daisuke Yamaguchi

ALDETE Corporation (JAPAN)

- 09:00 ~ 09:20 4-1 Technologies and Trends Related to Intelligent Power Module (IPM)

- Gourab Majumdar
Mitsubishi Electric Corporation (JAPAN)
- 09:20 ~ 09:40 4-2 Bridges from Chips to Packages
 Tadaharu Minato
Mitsubishi Electric Corporation (JAPAN)
- 09:40 ~ 09:55 4-3 Electric Vehicle – The New Revolution
 Hemalatha Annamalai
Ampere Vehicles Pte Ltd (INDIA)

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09:55 ~ 10:20 Coffee Break

10:20 ~ 12:30 Session 5: 3D Integration -Part2-

(Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)

Chair: Hisao Kasuga

NEC Electronics Corporation (JAPAN)

Japan Electronics and Information Technology Industries Association (JEITA) (JAPAN)

- 10:20 ~ 10:35 5-1 RENESAS SiP Future 3D Technology
 Masashi Umino
Renesas Technology Corp. (JAPAN)
- 10:35 ~ 10:50 5-2 EDA tools for Analog/Mixed-Signal IC and MEMS Layout Design for Circuit Design,
 Layout Design and Layout Verification
 Yoshiko Shimogaki
Tanner Research Japan K.K. (JAPAN)
- 10:50 ~ 11:05 5-3 Report on Active Device Embedding Technology using ESC5 Process
 S.Sasaguri, H.Eifuku, H.Maruo, K.Motomura, T.Sakai
Panasonic Factory Solutions Co., Ltd. (JAPAN)
- 11:05 ~ 11:20 5-4 Electrical Modeling of Power Device Package with Q3D Extractor
 Toru Watanabe
Ansoft Japan K.K

11:20 ~ 11:30 Short Break

- 11:30 ~ 11:45 5-5 Electrochemical process for through via/bump formation without CMP and Lithographic
 Processes
 Jae-Ho Lee
Hongik University (KOREA)
- 11:45 ~ 12:00 5-6 SUSS MicroTec in 3D Integration
 Raymond Lau

SUSS MicroTec Japan (JAPAN)

- 12:00 ~ 12:15 5-7 Sidewall Insulator Film Deposition for the Through Silicon Via (TSV) Process Using Cathode Coupled PE-CVD
Y. Kusuda, T. Minaguchi, T. Miyashita and S. Motoyama
SAMCO, Inc. (JAPAN)
- 12:15 ~ 12:30 5-8 Impact of the rf-Glow Discharge Technology on Surface and Cross-Section Analyses
Toru Kaga* and Kenny Iwasaki**
Nanoscale Company (JAPAN)

12:30 ~ 13:30 Lunch Break

13:30 ~ 15:00 Session 6: Taiwan Session

(Knowledge Cluster Initiative (The 2nd Stage) Expansion Program, The 4th Workshop)

Chair: Akihiro Kawaguchi

Fukuoka Industry, Science & Technology Foundation (JAPAN)

- 13:30 ~ 14:00 6-1 Taiwan 3DIC Value Chain: The Next Revolution for Taiwan Semiconductor Industries
Ian Yi-Jen Chan
Electronics and Optoelectronics Research Lab., Industrial Technology Research Institute (ITRI) (TAIWAN)
- 14:00 ~ 14:20 6-2 Semiconductor Business in Taiwan
Yoshinori Sasaki
MARUBUN TAIWAN, INC. (TAIWAN)
- 14:20 ~ 14:40 6-3 High Speed DRAM Package Bandwidth Simulation
Fan, Wen-Jeng
Powertech Technology Inc. (PTI) (TAIWAN)
- 14:40 ~ 15:00 6-4 SoC Design and Turnkey Services in Taiwan
James Cheng
Global Unichip Corporation (GUC) (TAIWAN)

15:00 ~ 15:30 Coffee Break

15:30 ~ 17:10 Session 7*: India Session

Chair: Hajime Tomokage

Fukuoka University (JAPAN)

- 15:30 ~ 15:50 7-1 India: The Rising Player in The World Electronics Design Stage
Poornima Shenoy
India Semiconductor Association (ISA) (INDIA)
- 15:50 ~ 16:10 7-2 India Semiconductor Vision ISV 2020
Pradip K. Dutta

Synopsys (I) Pvt Ltd. (INDIA)

16:10 ~ 16:30 7-3 Automotive Systems- Semiconductor Perspectives: Analog Function Realization- Challenges and Potential

R. Ramabrahmam

KPIT Cummins Infosystems Ltd. (INDIA)

16:30 ~ 16:50 7-4 Exploring Business Opportunities for Kyushu in Collaboration with Indian Partners

Tetsuya Tsuruta

PATNI Computer Systems Ltd. (INDIA)

16:50 ~ 17:10 7-5 “eInfochips” – Your Strategic Partner for your Electronics Design, Development and Verifications

Satoshi Yamada

eInfochips. Ltd. (INDIA)

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17:30 ~ 19:00 Session 8: Poster Session with Wines @ Argos

Chair: KS Dorai Arasu

InfoSree Technologies Pvt. Ltd. (INDIA)

Friday 13th, November

Excursion Schedule

07:30 JAL Resort Sea Hawk Hotel Fukuoka, 1F Robby
10:00 ~ 12:00 Tokyo Electron Kyushu Limited, Head Office, Goshi Plant
12:00 ~ 13:00 Lunch
13:30 ~ 15:30 Mitsubishi Electric Corporation, Power Device Works, Kumamoto Plant
17:30 Fukuoka Airport, Hakata Station

Poster Exhibition (Wednesday 11th - Thursday 12th)

Ansoft Japan K.K.	ALDETE Corporation
Alpha Design Co., Ltd.	BEAMSENSE Co., Ltd.
Daiichi Institution Industry Co., Ltd.	eInfochips. Ltd.
ELIA Co., Ltd.	Espec Kyushu Corp.
Fukuden Shizai Co., Ltd.	Kyushuokano Electronics Co., Ltd.
Mitsuboshi Diamond Industrial Co., Ltd	NAGASE & CO., LTD.
Namiki Precision Jewel Co., Ltd./Adamant Kogyo Co., Ltd.	Nikon Tec Corporation
Panasonic Factory Solutions Co., Ltd.	Renesas Technology Corp.
SAMCO Inc.	Shintec Co., Ltd.
Suss Microtec KK	Tanner Research Japan K.K.
TOPCON Corporation	Toray Engineering Co., Ltd.
Ushio. Inc.	Wabo Electronics Co.,Ltd.
WALTS Co., Ltd.	

(Alphabetical order)